

# **Product Change Notification**



Product Group: Vishay Siliconix/Sep 22, 2014/PCN- SIL-0822014 Rev1

#### **Fab Site Transfer**

**DESCRIPTION OF CHANGE:** For the 300M cell products listed in this notification we are changing the Fab site from Santa Clara, California, USA and Global Foundries, Singapore to Vishay Siliconix Itzehoe GmbH (VSIG) located at Fraunhoferstraße 1, 25524 Itzehoe, Germany. VSIG has been an automotive Fab with ISO14001 and TS16949 certifications for more than 10 years.

No changes have been made to the silicon process technology, wafer test, assembly process and final test. Production of the affected part from Santa Clara Fab and Global Foundries will be terminated per the time schedule in this notification and last time buy orders must be received within the specified timeframe.

**CLASSIFICATION OF CHANGE:** Fab Site Transfer

REASON FOR CHANGE: Closure of Santa Clara Fab and Global Foundries

EXPECTED INFLUENCE ON QUALITY/RELIABILTY/PERFORMANCE: None

**PRODUCT CATAGORY:** Automotive MOSFETs

VISHAY PART NUMBERS AFFECTED: Affected part numbers are listed on the following page

VISHAY BRAND(s): Vishay-Siliconix

**QUALIFICATION DATA:** All products listed in this notification are manufactured using 300M cell process technology which is AEC Q101 qualified. Please refer to the subsequent pages to see summary of qualification report for the lead 300M product from VSIG Fab. Qualification report for individual part type will be provided in PPAP and upon request.

**SAMPLE AVAILABILITY:** Schedule of availability of qualified samples from VSIG Fab is listed on following page. For samples, please email <a href="mailto:automos.pcn@Vishay.com">automos.pcn@Vishay.com</a> with subject PCN-SIL-0822014 and include date by which samples are needed, required quantity and ship-to address.

**TIME SCHEDULE:** Last time buy orders are required by 31-Dec-2014 for parts manufactured at Global Foundries. For parts manufactured at Santa Clara Fab, last time buy order dates are listed for each part number on the following page. Last time ship dates are the same for both Global Foundries and Santa Clara Fab material.

ISSUED BY: Shishir Rai, Product Marketing Manager (E-mail: Shishir.Rai@Vishay.com)

For further information, please contact your regional Vishay office.

The Americas

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Vishay Intertechnology, Inc.



# **Product Change Notification**



Product Group: Vishay Siliconix/Sep 22, 2014/PCN- SIL-0822014 Rev1

#### **VISHAY PART NUMBERS AFFECTED:**

Affected Vishay Part Number	Qualified Sample Availability Month	Last Time Buy Date (for Santa Clara Fab only)	Last Time Ship Date
SQA410EJ-T1-GE3	Available	30-Mar-15	30-Sep-15
SQC120N04-1M7LDFFR	Available	30-Mar-15	30-Sep-15
SQM120N03-1M5L-GE3	Available	30-Mar-15	30-Sep-15
SQD50N04-4M1-GE3	Sep-14	30-Mar-15	30-Sep-15
SQJ422EP-T1-GE3	Dec-14	30-Jun-15	30-Dec-15
SQJ912AEP-T1-GE3	Jan-15	30-Jun-15	30-Dec-15

#### **QUALIFICATION REPORT:**

Qualification report for lead product SQM120N04-1M7L-GE3 manufactured using 300M cell process technology at VSIG Fab is provided in subsequent pages. Qualification report for the replacement parts listed above will be provided in PPAP and upon request.



### **Production Part Approval - Environmental Test Summary**

 Supplier:
 Vishay Siliconix
 General Specification:
 AEC-Q101

 Supplier Part Number:
 SQM120N04-1M7L-GE3
 Assembly Site:
 Kaohsiung, Taiwan ROC

 Process Technology:
 300M Cell N-Channel G4
 Fab Site:
 VSIG, Itzehoe Germany

Test	Test Conditions	Lots		# Failed	Requirements	Remarks
		*	All	0		
	LOTE			•	8000 0	
	J-STD-020C		All	0	@260 C	
	Electricals per drawing	*	ΛII	0		
workmanship. Electrical test not required.	Liectricals per drawing		All	0		Evaluation
						1.
Parametric Verification		3	30	0		2.
						3.
						5 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0
user/supplier specification with device reverse biased to 100%	175C 1000 HRS	1	77	0	DEVICE SPECIFIC:	Evaluation
						1. 1380274
						1. 1300274 2.
hours, and 1000 hours. JESD22 A108						3.
						J.
High Temperature Gate Bias (HTGB):						
, , ,	175C 1000 HRS	1	77	0	DEVICE SPECIFIC:	Evaluation
						1. 1380274
•						2.
,						3.
Temperature Cyclings IESD22 A 104 Air to air (See						Evaluation
	1000CVC 65C 150C	1	77	0	DEVICE SPECIFIC:	1. 1380274
Reliability Froduct Data Suffillary).	1000010-030 ~ 1500	'	′ ′	U	DEVICE SPECIFIC.	2.
						3.
						Evaluation
Autoplaya (Progrupa Dot)	Ta = 121C, RH = 100%, 15psig, 96	1	77	0	DEVICE ODECIEIO	1. 1380274
Autociave (Pressure Pot)	hrs: Test before and after AC.	!	//	U	DEVICE SPECIFIC:	2.
						3.
						Evaluation
	4000 0504 BH 400 HB0				DEV//OF ODEOUTIO	1. 1380274
HASI	130C, 85% RH, 100 HRS	1	77	0	DEVICE SPECIFIC:	2.
						3.
						Evaluation
Intermittent Operational Life (Power Cycle)						1. 1380274
Delta Ti = 100C	8572 CYC	1	77	0	DEVICE SPECIFIC:	2.
	prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  High Temperature Reverse Bias (HTRB): 1000 hours max rated junction temperature specified in the user/supplier specification with device reverse biased to 100% of maximum breakdown voltage specified or max junction temperature to avoid thermal runaway. TEST before, at 500 hours, and 1000 hours. JESD22 A108  High Temperature Gate Bias (HTGB): 1000 hours at Ta = device maximum rated junction temperature with gate biased at 100% of maximum gate voltage rating indicated in the detail specification with device OFF. TEST before, at 500 hours, and 1000 hours. JESD22 A108  Temperature Cycling: JESD22 A-104, Air to air. (See Reliability Product Data Summary):	Pre-conditioning: Performed on surface mount devices (SMDs) prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  High Temperature Reverse Bias (HTRB): 1000 hours max rated junction temperature specified in the user/supplier specification with device reverse biased to 100% of maximum breakdown voltage specified or max junction temperature to avoid thermal runaway. TEST before, at 500 hours, and 1000 hours. JESD22 A108  High Temperature Gate Bias (HTGB): 1000 hours at Ta = device maximum rated junction temperature with gate biased at 100% of maximum gate voltage rating indicated in the detail specification with device OFF. TEST before, at 500 hours, and 1000 hours. JESD22 A108  Temperature Cycling: JESD22 A-104, Air to air. (See Reliability Product Data Summary):  Ta = 121C, RH = 100%, 15psig, 96 hrs: Test before and after AC.	Pre-conditioning: Performed on surface mount devices (SMDs) prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  High Temperature Reverse Bias (HTRB): 1000 hours max rated junction temperature specified in the user/supplier specification with device reverse biased to 100% of maximum breakdown voltage specified or max junction temperature to avoid thermal runaway. TEST before, at 500 hours, and 1000 hours. JESD22 A108  High Temperature Gate Bias (HTGB): 1000 hours at Ta = device maximum rated junction temperature with gate biased at 100% of maximum gate voltage rating indicated in the detail specification with device OFF. TEST before, at 500 hours, and 1000 hours. JESD22 A108  Temperature Cycling: JESD22 A-104, Air to air. (See Reliability Product Data Summary):  Ta = 121C, RH = 100%, 15psig, 96 hrs: Test before and after AC.	Pre-conditioning: Performed on surface mount devices (SMDs) prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  Electricals per drawing  * All  Parametric Verification  High Temperature Reverse Bias (HTRB): 1000 hours max rated junction temperature specified in the user/supplier specification with device reverse biased to 100% of maximum breakdown voltage specified or max junction temperature to avoid thermal runaway. TEST before, at 500 hours, and 1000 hours. JESD22 A108  High Temperature Gate Bias (HTGB): 175C 1000 HRS  1 77  175C 1000 HRS  1 77	Pre-conditioning: Performed on surface mount devices (SMDS) prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  Electricals per drawing  * All 0  Electricals per drawing  * All 0  Parametric Verification  3 30 0  High Temperature Reverse Bias (HTRB): 1000 hours max rated junction temperature specified in the user/supplier specification with device reverse biased to 100% of maximum breakdown voltage specified or max junction temperature to avoid thermal runaway. TEST before, at 500 hours, and 1000 hours. JESD22 A108  High Temperature Gate Bias (HTGB): 1000 hours at Ta = device maximum rated junction temperature with gate biased at 100% of maximum gate voltage rating indicated in the detail specification with device OFF. TEST before, at 500 hours, and 1000 hours. JESD22 A108  Temperature Cycling: JESD22 A-104, Air to air. (See Reliability Product Data Summary):  1000 CYC -65C ~ 150C  11 77 0  Ta = 121C, RH = 100%, 15psig, 96 hrs: Test before and after AC.	Pre-conditioning: Performed on surface mount devices (SMDs) prior to Temp Cycle, Autoclave, HAST, Power Cycle stresses only  External Visual: Inspect device construction, marking and workmanship. Electrical test not required.  Parametric Verification  Electricals per drawing  * All 0  @260 C  ### All 0  ### All 0  ### All 0  ### All 0  ### Parametric Verification  ### All 0  ### All 0  ### Parametric Verification  ### All 0  ### All 0  ### Parametric Verification  ### All 0  ### All 0  ### Parametric Verification  ### Parametric Verification  ### All 0  ### Parametric Verification  ### Parametric Verif



### **Production Part Approval - Environmental Test Summary**

Supplier:Vishay SiliconixGeneral Specification:AEC-Q101Supplier Part Number:SQM120N04-1M7L-GE3Assembly Site:Kaohsiung, Taiwan ROCProcess Technology:300M Cell N-Channel G4Fab Site:VSIG, Itzehoe Germany

			# of			Additional	
ltem	Test	Test Conditions	Lots	S.S.	# Failed	Requirements	Remarks
	ESD Characterization - NOTE: Unless protected by internal						Evaluation
	ESD-specific protection circuitry, MOSFETs only have intrinsic						1. 1340321
						Passed 7.00KV MIL-STD-	
	protection that is dependent on the size of die and other				_		
	environmental and physical factors, making them very sensitive	Human Model	1	10	0	883D	
11	to potential ESD damage and industry standard precautions						
	should be taken not to expose them to any ESD. Due to the						
	small size of MOSFET packages, these devices are generally						
	not affected by the Charged Device Model, and we therefore						
	substitute Machine Model testing					Passed 1.30KV MIL-STD-	
	substitute Machine Model testing.	Machine Model	1	10	0	883D	
							Evaluation
12	Destructive Physical Analysis	AEC-Q101-004 Section 4	1	2X2	0		1. 1340321
·	Physical Dimensions: Verify physical dimensions to the						
	applicable user device packaging specification for dimensions						
		O D D					0 0000
13		Siliconix Print Dimensions	N/A	N/A	N/A		See PPAP
14	Termianl Strength		N/A	N/A	N/A		SMD Device
15	Resistance to Solvent		N/A	N/A	N/A		Laser Marked
16	Constant Acceleration		N/A	N/A	N/A		SMD Device
17	Vibration Variable Frequency		N/A	N/A	N/A		SMD Device
18	Mechanical Shock		N/A	N/A	N/A		SMD Device
19	Hermiticity		N/A	N/A	N/A		SMD Device
		JECD22 B 400 A 2000 40000 Took					Evaluation
		JESD22 B-106-A, 260C, 10sec. Test			_		1. 1380274
20	Resistance to Solder Heat (Solder Dunk)	before and after RSH. SMD devices	1	50	0	DEVICE SPECIFIC:	2.
		shall be fully submerged during test					3.
							3.
							Evaluation
21	Solderability	Pb-Free - JESD201	1	15	0	DEVICE SPECIFIC:	1. 1380274
21	Solderability	PD-FIEE - JESDZUT	1	15	U	DEVICE SPECIFIC.	2.
							3.
							Evaluation
							1. 1440135
22	Thermal Resistance	JESD24-3	1	10	0	DEVICE SPECIFIC:	2.
							3.
							S. Evaluation
							1. 1380274
			1	40	0	DEVICE SPECIFIC:	
00	M/: D 10: 4	MIL OTD 750 M (I. 10007		-			2.
23	Wire Bond Strength	MIL-STD-750 Method 2037					3.
						Deviadia complina or	
٠,	D 101	AEO 0404 000	N1/4	B 1 / 2		Periodic sampling on	0 0 1 1 1 2 5525
24	Bond Shear	AEC-Q101-003	N/A	N/A	N/A	production units	See Cpk data in PPAP



## **Production Part Approval - Environmental Test Summary**

Supplier: Supplier Part Number:	Vishay Siliconix SQM120N04-1M7L-GE3	General Specification: Assembly Site:	AEC-Q101 Kaohsiung, Taiwan ROC
Process Technology:	300M Cell N-Channel G4	Fab Site:	VSIG, Itzehoe Germany

ltem	Test	Test Conditions	# of Lots	S.S.	# Failed	Additional Requirements	Remarks
0.5	Die Oberen	MII. OTD 750 M-th - 1 0047	1	10	0	DEVICE SPECIFIC:	Evaluation 1. 1380274 2.
25 26	Die Shear UIS Testing	MIL-STD-750 Method 2017  Non-destructive mode	100%	100%	0		100% tested at Final Test
27	Dielectric Integrity	Non-destructive mode	100%	100%	0		100% tested at Final Test

Note: \* = Samples taken from many lots

Prepared by: Julan Chen	
Reliability Engineer	5/16/2014
Incliability Engineer	3/10/2014

Approved by: Arthur	
Director of Reliability	5/16/2014